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# FQP6N60C/FQPF6N60C

#### **600V N-Channel MOSFET**

#### **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction, electronic lamp ballasts based on half bridge topology.

#### **Features**

- 5.5A, 600V,  $R_{DS(on)}$  = 2.0 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 16 nC)
- Low Crss (typical 7 pF)
- Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability



## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQP6N60C	FQPF6N60C	Units
$V_{DSS}$	Drain-Source Voltage		600		V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		5.5	5.5 *	Α
	- Continuous (T <sub>C</sub> = 100°C)		3.3	3.3 *	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	22	22 *	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30		V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note		300		mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	5.5		Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		12.5		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns
$P_D$	Power Dissipation (T <sub>C</sub> = 25°C)		125	40	W
	- Derate above 25°C		1.0	0.31	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300		°C

<sup>\*</sup> Drain current limited by maximum junction temperature.

#### **Thermal Characteristics**

Symbol	Parameter	FQP6N60C	FQPF6N60C	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.0	3.2	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	racteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600			V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced t	o 25°C		0.6		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V				1	μΑ
		V <sub>DS</sub> = 480 V, T <sub>C</sub> = 125°C				10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V				100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.75 A			1.7	2.0	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 2.75 A	(Note 4)		4.8		S
<b>Dynam</b> C <sub>iss</sub>	ic Characteristics Input Capacitance	V - 25 V V - 0 V			620	810	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			65	85	pF
C <sub>rss</sub>	Reverse Transfer Capacitance				7	10	pF
	na Characteriation						
t <sub>d(on)</sub>	ng Characteristics Turn-On Delay Time				15	40	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 300 \text{ V}, I_{D} = 5.5 \text{A},$			45	100	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$R_G = 25 \Omega$ (Note 4, 5)			45	100	ns
t <sub>f</sub>	Turn-Off Fall Time				45	100	ns
Q <sub>q</sub>	Total Gate Charge	\(\text{\chi}\)			16	20	nC
Q <sub>gs</sub>	Gate-Source Charge	$V_{DS} = 480 \text{ V}, I_{D} = 5.5 \text{A},$ $V_{GS} = 10 \text{ V}$			3.5		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4, 5)			6.5		nC
	, , , , , , , , , , , , , , , , , , ,						
Drain-S	Source Diode Characteristics at Maximum Continuous Drain-Source Did	<u>_</u>				5.5	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current					22	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 5.5 A				1.4	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_S = 5.5 \text{ A},$			310		ns
		1 00 - , 0,				l .	

- Notes: 
  1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 18.2mH,  $I_{AS}$  = 5.5 A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 Ω, Starting  $T_{J}$  = 25°C 3.  $I_{SD}$  ≤ 5.5A, di/dt ≤ 200A/μs,  $V_{DD}$  ≤ BV<sub>DSS</sub>, Starting  $T_{J}$  = 25°C 4. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

# Typical Characteristics Typical Characteristics (Continued)

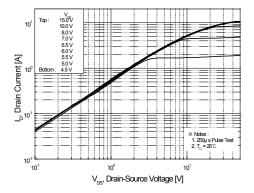


Figure 1. On-Region Characteristics

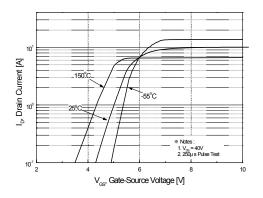


Figure 2. Transfer Characteristics

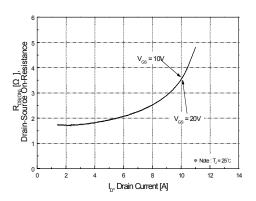


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

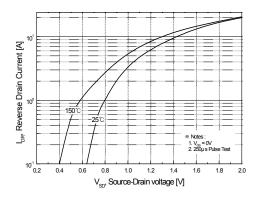


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

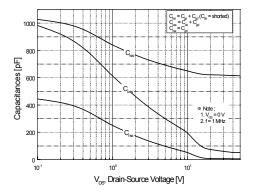


Figure 5. Capacitance Characteristics

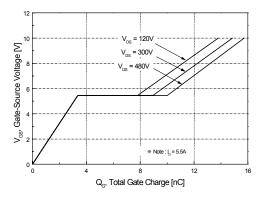


Figure 6. Gate Charge Characteristics

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# **Typical Characteristics** (Continued)

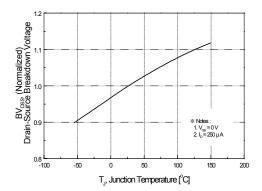


Figure 7. Breakdown Voltage Variation vs Temperature

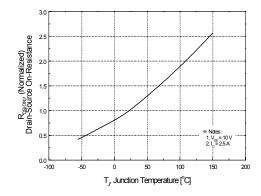


Figure 8. On-Resistance Variation vs Temperature

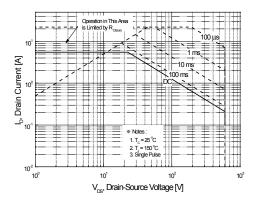


Figure 9-1. Maximum Safe Operating Area for FQP6N60C

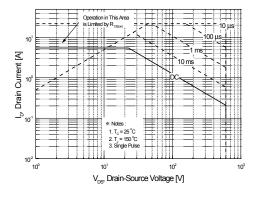


Figure 9-2. Maximum Safe Operating Area for FQPF6N60C

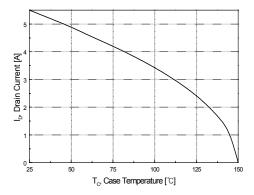


Figure 10. Maximum Drain Current vs Case Temperature

# Typical Characteristics (Continued)

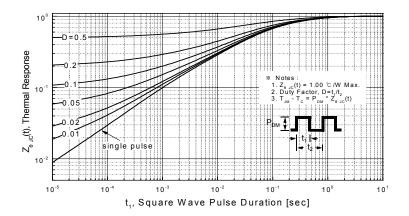


Figure 11-1. Transient Thermal Response Curve for FQP6N60C

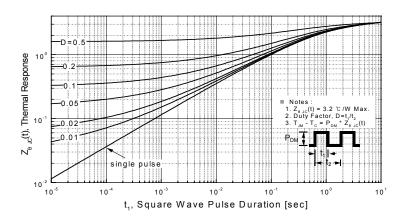
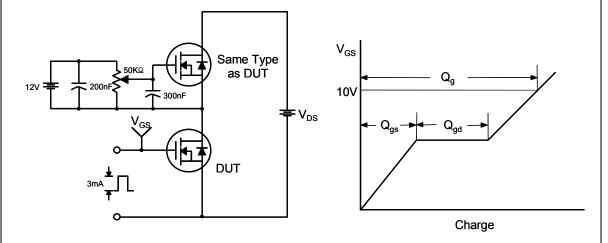


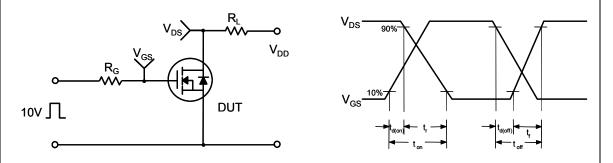
Figure 11-2. Transient Thermal Response Curve for FQPF6N60C

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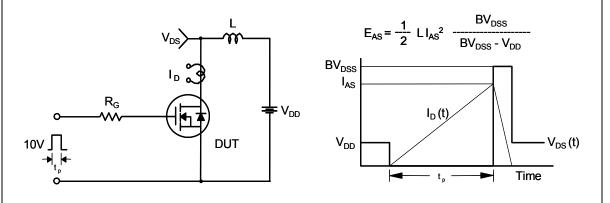
### **Gate Charge Test Circuit & Waveform**



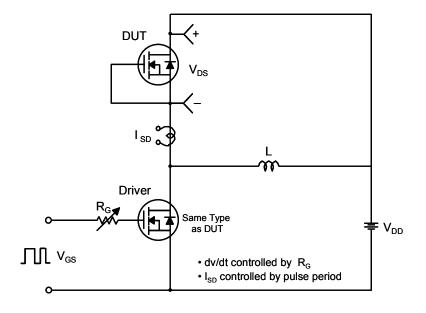
#### **Resistive Switching Test Circuit & Waveforms**

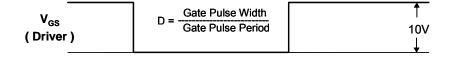


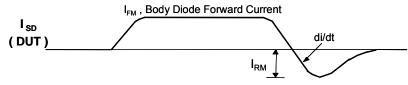
#### **Unclamped Inductive Switching Test Circuit & Waveforms**



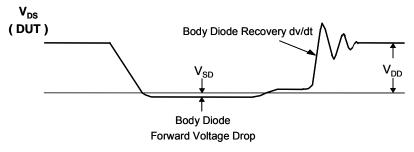
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms





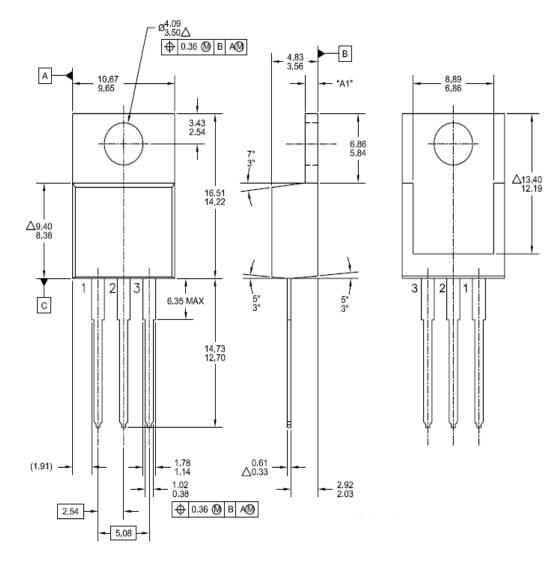


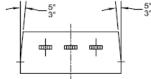
Body Diode Reverse Current



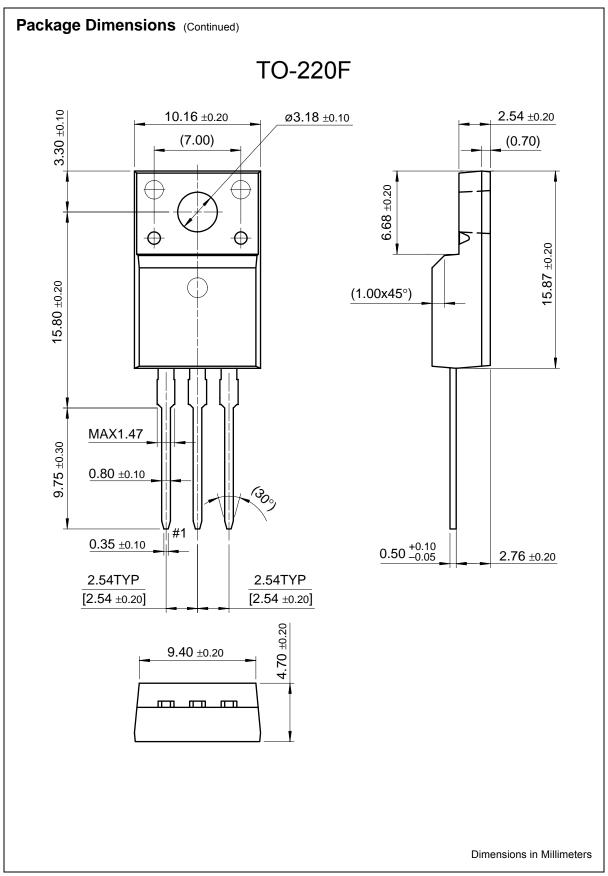


TO - 220





Dimensions in Millimeters



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